--BRIEF DESCRIPTION OF THE DRAWINGS

A1

FIG. 1 shows a silicon single wafer according to the invention.--

Please amend page 17 of the Specification between lines 7 and 8 to recite the new paragraph:

K2-

--Referring to FIG. 1, the semiconductor wafer 1 preferably has a front surface 3, a back surface 5, an imaginary central plane 7 between the front and back surfaces, and a circumferential edge 2 joining the front surface 3 and the back surface 5. The terms "front" and "back" in this context are used to distinguish the two major, generally planar surfaces of the wafer 1. There is an epitaxial layer 9 on the front surface 3 of the pretreated semiconductor wafer 1.--

A Marked-Up Version of Specification pages 16 and 17 is enclosed.